PALM Intranet

Application
Number [   ] [SEARCH]

IDS Flag Clearance for Application [10790723   ]

**IDS
Information**

	Content	Mailroom Date	Entry Number	IDS Review	Reviewer
	M844	11-16-2005	23	☑	11-22-2005 10:31:50 lhinton

[UPDATE]

Refine Search

Search Results -

Terms	Documents
L26 and (via$ near8 wafer)	11

Database:

```
US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins
```
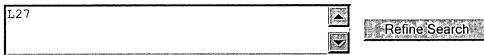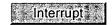
Search:

```
L27
```

[Refine Search]

[Recall Text] [Clear] [Interrupt]

Search History

DATE: **Wednesday, March 15, 2006**   Printable Copy   Create Case

Set Name side by side	Query	Hit Count	Set Name result set
DB=PGPB; PLUR=YES; OP=OR			
L27	L26 and (via$ near8 wafer)	11	L27
L26	(micro near5 (device or chip or die) near15 wafer) and ((cavity near5 (wafer)) and cavity near5 (cap or encapsulant or cover))	61	L26
DB=USPT; PLUR=YES; OP=OR			
L25	(micro near5 (device or chip or die) near15 wafer) and ((cavity near5 (wafer)) and cavity near5 (cap or encapsulant or cover))	34	L25
L24	L12 and ((cavity near5 (wafer)) and cavity near5 (cap or encapsulant or cover))	3	L24
L23	L12 and ((cavity near5 (substrate)) and cavity near5 (cap or encapsulant or cover))	4	L23
L22	L12 and ((cavity near5 (substrate)) and 9cavity near5 (cap or encapsulant or cover))	0	L22
L21	5668033 and ("51")	15	L21

DB=PGPB; PLUR=YES; OP=OR

L20	L19 and "peripheral metal"	1	L20
L19	L18 and perimeter	1	L19
L18	20050073040	1	L18

DB=USPT; PLUR=YES; OP=OR

L17	(bump near5 pad$) near7 packaging	122	L17
L16	L15 and "338"	1	L16
L15	6114191 and pads	4	L15
L14	L13 and (external near6 pad$)	15	L14
L13	L12 and (cap or encapsul$6)	123	L13
L12	L11 and (via$ near8 wafer)	639	L12
L11	L10 and (pads near6 surface near8 wafer)	2718	L11
L10	((device or chip or die)) near15 wafer	57123	L10
L9	L8 and (via$ near8 wafer)	6	L9
L8	L7 and ((pad$ near6 surface) near10 wafer)	32	L8
L7	(micro near5 (device or chip or die)) near15 wafer	616	L7
L6	L5 and (via$ near8 wafer)	6	L6
L5	L4 and (pads near6 surface near8 wafer)	26	L5
L4	(micro near5 (device or chip or die)) near8 wafer	536	L4
L3	6271081	6	L3
L2	6777263	4	L2
L1	5144412	12	L1

END OF SEARCH HISTORY